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### What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

### Applications of "[Embedded - Microcontrollers](#)"

#### Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	-
Peripherals	POR, WDT
Number of I/O	5
Program Memory Size	1.75KB (1K x 14)
Program Memory Type	FLASH
EEPROM Size	128 x 8
RAM Size	64 x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5.5V
Data Converters	A/D 4x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	8-DIP (0.300", 7.62mm)
Supplier Device Package	8-PDIP
Purchase URL	<a href="https://www.e-xfl.com/product-detail/microchip-technology/pic12f675-i-p">https://www.e-xfl.com/product-detail/microchip-technology/pic12f675-i-p</a>

## 8-Pin Flash-Based 8-Bit CMOS Microcontroller

### High-Performance RISC CPU:

- Only 35 Instructions to Learn
  - All single-cycle instructions except branches
- Operating Speed:
  - DC – 20 MHz oscillator/clock input
  - DC – 200 ns instruction cycle
- Interrupt Capability
- 8-Level Deep Hardware Stack
- Direct, Indirect, and Relative Addressing modes

### Special Microcontroller Features:

- Internal and External Oscillator Options
  - Precision Internal 4 MHz oscillator factory calibrated to  $\pm 1\%$
  - External Oscillator support for crystals and resonators
  - 5  $\mu$ s wake-up from Sleep, 3.0V, typical
- Power-Saving Sleep mode
- Wide Operating Voltage Range – 2.0V to 5.5V
- Industrial and Extended Temperature Range
- Low-Power Power-on Reset (POR)
- Power-up Timer (PWRT) and Oscillator Start-up Timer (OST)
- Brown-out Detect (BOD)
- Watchdog Timer (WDT) with Independent Oscillator for Reliable Operation
- Multiplexed MCLR/Input Pin
- Interrupt-on-Pin Change
- Individual Programmable Weak Pull-ups
- Programmable Code Protection
- High Endurance Flash/EEPROM Cell
  - 100,000 write Flash endurance
  - 1,000,000 write EEPROM endurance
  - Flash/Data EEPROM Retention: > 40 years

### Low-Power Features:

- Standby Current:
  - 1 nA @ 2.0V, typical
- Operating Current:
  - 8.5  $\mu$ A @ 32 kHz, 2.0V, typical
  - 100  $\mu$ A @ 1 MHz, 2.0V, typical
- Watchdog Timer Current
  - 300 nA @ 2.0V, typical
- Timer1 Oscillator Current:
  - 4  $\mu$ A @ 32 kHz, 2.0V, typical

### Peripheral Features:

- 6 I/O Pins with Individual Direction Control
- High Current Sink/Source for Direct LED Drive
- Analog Comparator module with:
  - One analog comparator
  - Programmable on-chip comparator voltage reference (CVREF) module
  - Programmable input multiplexing from device inputs
  - Comparator output is externally accessible
- Analog-to-Digital Converter module (PIC12F675):
  - 10-bit resolution
  - Programmable 4-channel input
  - Voltage reference input
- Timer0: 8-Bit Timer/Counter with 8-Bit Programmable Prescaler
- Enhanced Timer1:
  - 16-bit timer/counter with prescaler
  - External Gate Input mode
  - Option to use OSC1 and OSC2 in LP mode as Timer1 oscillator, if INTOSC mode selected
- In-Circuit Serial Programming™ (ICSP™) via two pins

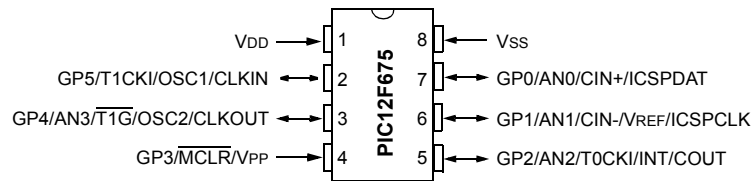
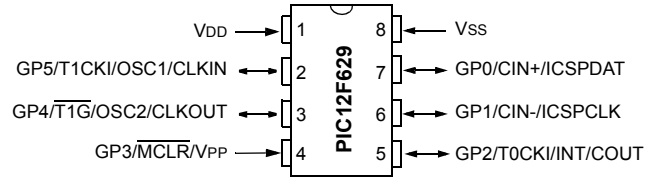
Device	Program Memory	Data Memory		I/O	10-bit A/D (ch)	Comparators	Timers 8/16-bit
	Flash (words)	SRAM (bytes)	EEPROM (bytes)				
PIC12F629	1024	64	128	6	—	1	1/1
PIC12F675	1024	64	128	6	4	1	1/1

\* 8-bit, 8-pin devices protected by Microchip's Low Pin Count Patent: U.S. Patent No. 5,847,450. Additional U.S. and foreign patents and applications may be issued or pending.

# PIC12F629/675

## Pin Diagrams

### 8-pin PDIP, SOIC, DFN-S, DFN



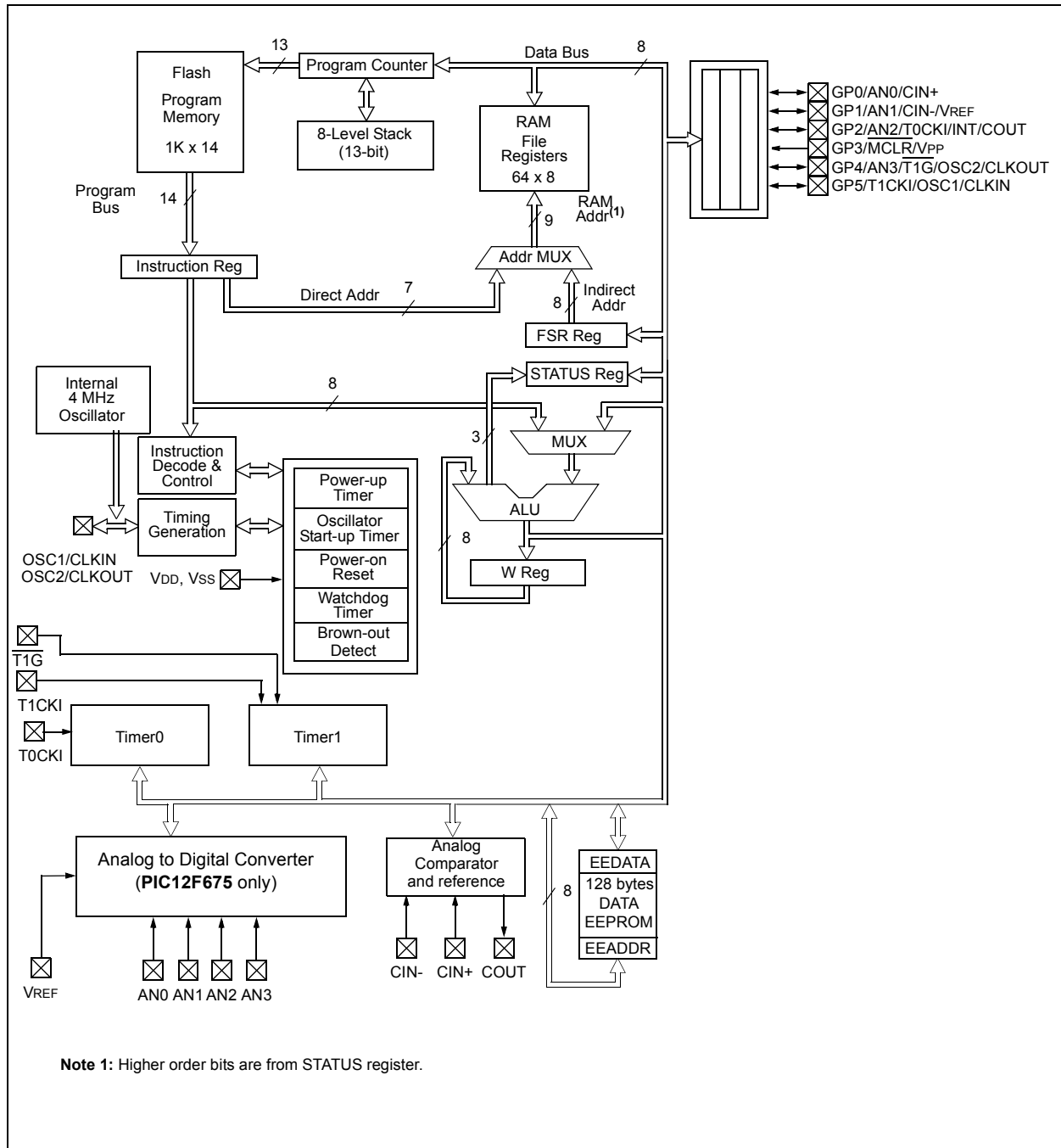
## 1.0 DEVICE OVERVIEW

This document contains device specific information for the PIC12F629/675. Additional information may be found in the PIC® Mid-Range Reference Manual (DS33023), which may be obtained from your local Microchip Sales Representative or downloaded from the Microchip web site. The Reference Manual should be considered a complementary document to this Data

Sheet, and is highly recommended reading for a better understanding of the device architecture and operation of the peripheral modules.

The PIC12F629 and PIC12F675 devices are covered by this Data Sheet. They are identical, except the PIC12F675 has a 10-bit A/D converter. They come in 8-pin PDIP, SOIC, MLF-S and DFN packages. Figure 1-1 shows a block diagram of the PIC12F629/675 devices. Table 1-1 shows the pinout description.

**FIGURE 1-1: PIC12F629/675 BLOCK DIAGRAM**



# PIC12F629/675

**TABLE 2-1: SPECIAL FUNCTION REGISTERS SUMMARY (CONTINUED)**

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOD	Page
<b>Bank 1</b>											
80h	INDF <sup>(1)</sup>	Addressing this Location uses Contents of FSR to Address Data Memory								0000 0000	20,61
81h	OPTION_REG	GPPU	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0	1111 1111	14,31
82h	PCL	Program Counter's (PC) Least Significant Byte								0000 0000	19
83h	STATUS	IRP <sup>(2)</sup>	RP1 <sup>(2)</sup>	RP0	T0	PD	Z	DC	C	0001 1xxx	14
84h	FSR	Indirect Data Memory Address Pointer								xxxx xxxx	20
85h	TRISIO	—	—	TRISIO5	TRISIO4	TRISIO3	TRISIO2	TRISIO1	TRISIO0	--11 1111	21
86h	—	Unimplemented								—	—
87h	—	Unimplemented								—	—
88h	—	Unimplemented								—	—
89h	—	Unimplemented								—	—
8Ah	PCLATH	—	—	—	Write Buffer for Upper 5 bits of Program Counter				---	0 0000	19
8Bh	INTCON	GIE	PEIE	T0IE	INTE	GPIE	T0IF	INTF	GPIF	0000 0000	15
8Ch	PIE1	EEIE	ADIE	—	—	CMIE	—	—	TMR1IE	00-- 0--0	16
8Dh	—	Unimplemented								—	—
8Eh	PCON	—	—	—	—	—	—	POR	BOD	---- --0x	18
8Fh	—	Unimplemented								—	—
90h	OSCCAL	CAL5	CAL4	CAL3	CAL2	CAL1	CAL0	—	—	1000 00--	18
91h	—	Unimplemented								—	—
92h	—	Unimplemented								—	—
93h	—	Unimplemented								—	—
94h	—	Unimplemented								—	—
95h	WPU	—	—	WPU5	WPU4	—	WPU2	WPU1	WPU0	--11 -111	21
96h	IOC	—	—	IOC5	IOC4	IOC3	IOC2	IOC1	IOC0	--00 0000	23
97h	—	Unimplemented								—	—
98h	—	Unimplemented								—	—
99h	VRCON	VREN	—	VRR	—	VR3	VR2	VR1	VR0	0-0- 0000	42
9Ah	EEDATA	Data EEPROM Data Register								0000 0000	49
9Bh	EEADR	—	Data EEPROM Address Register							-000 0000	49
9Ch	EECON1	—	—	—	—	WRERR	WREN	WR	RD	---- x000	50
9Dh	EECON2 <sup>(1)</sup>	EEPROM Control Register 2								---- ----	50
9Eh	ADRESL <sup>(3)</sup>	Least Significant 2 bits of the Left Shifted A/D Result of 8 bits or the Right Shifted Result								xxxx xxxx	44
9Fh	ANSEL <sup>(3)</sup>	—	ADCS2	ADCS1	ADCS0	ANS3	ANS2	ANS1	ANS0	-000 1111	46,61

**Legend:** — = unimplemented locations read as '0', u = unchanged, x = unknown, q = value depends on condition, shaded = unimplemented

- Note** 1: This is not a physical register.  
 2: These bits are reserved and should always be maintained as '0'.  
 3: PIC12F675 only.

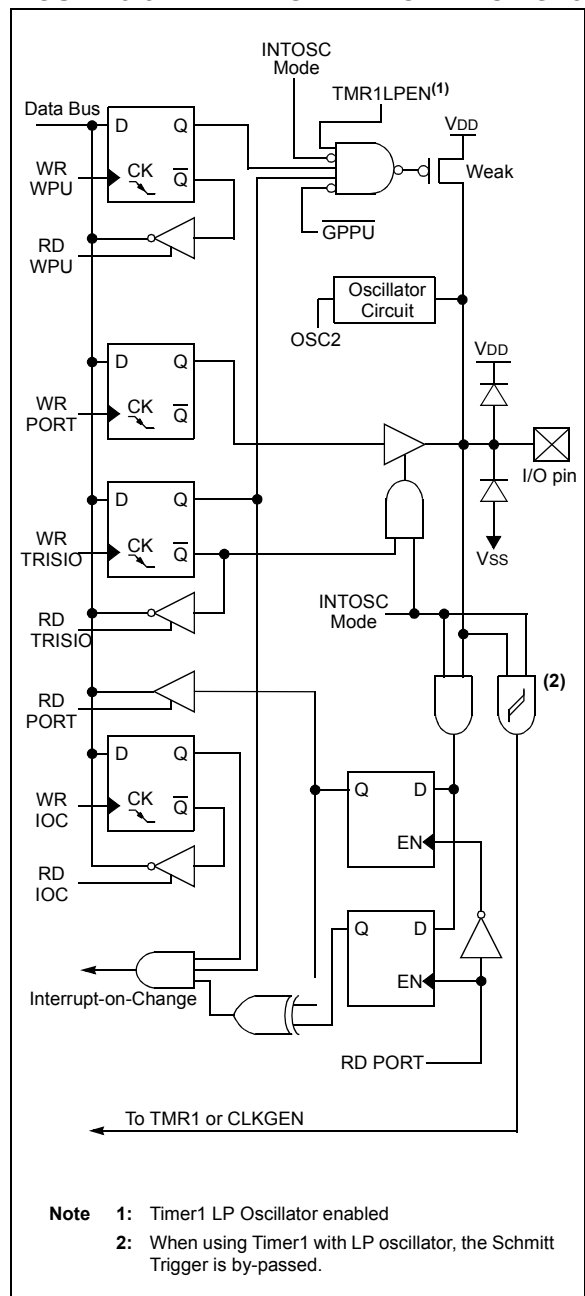
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### 3.3.6 GP5/T1CKI/OSC1/CLKIN

Figure 3-5 shows the diagram for this pin. The GP5 pin is configurable to function as one of the following:

- a general purpose I/O
- a TMR1 clock input
- a crystal/resonator connection
- a clock input

**FIGURE 3-5: BLOCK DIAGRAM OF GP5**



# PIC12F629/675

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NOTES:

# PIC12F629/675

## 7.3 A/D Operation During Sleep

The A/D converter module can operate during Sleep. This requires the A/D clock source to be set to the internal RC oscillator. When the RC clock source is selected, the A/D waits one instruction before starting the conversion. This allows the `SLEEP` instruction to be executed, thus eliminating much of the switching noise from the conversion. When the conversion is complete, the `GO/DONE` bit is cleared, and the result is loaded into the `ADRESH:ADRESL` registers. If the A/D interrupt is enabled, the device awakens from Sleep. If the A/D interrupt is not enabled, the A/D module is turned off, although the `ADON` bit remains set.

When the A/D clock source is something other than RC, a `SLEEP` instruction causes the present conversion to be aborted, and the A/D module is turned off. The `ADON` bit remains set.

## 7.4 Effects of Reset

A device Reset forces all registers to their Reset state. Thus the A/D module is turned off and any pending conversion is aborted. The `ADRESH:ADRESL` registers are unchanged.

**TABLE 7-2: SUMMARY OF A/D REGISTERS**

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOD	Value on all other Resets
05h	GPIO	—	—	GPIO5	GPIO4	GPIO3	GPIO2	GPIO1	GPIO0	--xx xxxx	--uu uuuu
0Bh, 8Bh	INTCON	GIE	PEIE	T0IE	INTE	GPIE	T0IF	INTF	GPIF	0000 0000	0000 000u
0Ch	PIR1	EEIF	ADIF	—	—	CMIF	—	—	TMR1IF	00-- 0--0	00-- 0--0
1Eh	ADRESH	Most Significant 8 bits of the Left Shifted A/D result or 2 bits of the Right Shifted Result								xxxx xxxx	uuuu uuuu
1Fh	ADCON0	ADFM	VCFG	—	—	CHS1	CHS0	GO	ADON	00-- 0000	00-- 0000
85h	TRISIO	—	—	TRISIO5	TRISIO4	TRISIO3	TRISIO2	TRISIO1	TRISIO0	--11 1111	--11 1111
8Ch	PIE1	EEIE	ADIE	—	—	CMIE	—	—	TMR1IE	00-- 0--0	00-- 0--0
9Eh	ADRESL	Least Significant 2 bits of the Left Shifted A/D Result or 8 bits of the Right Shifted Result								xxxx xxxx	uuuu uuuu
9Fh	ANSEL	—	ADCS2	ADCS1	ADCS0	ANS3	ANS2	ANS1	ANS0	-000 1111	-000 1111

**Legend:** x = unknown, u = unchanged, - = unimplemented read as '0'. Shaded cells are not used for A/D converter module.



# PIC12F629/675

## 9.2.3 EXTERNAL CLOCK IN

For applications where a clock is already available elsewhere, users may directly drive the PIC12F629/675 provided that this external clock source meets the AC/DC timing requirements listed in **Section 12.0 “Electrical Specifications”**. Figure 9-2 shows how an external clock circuit should be configured.

## 9.2.4 RC OSCILLATOR

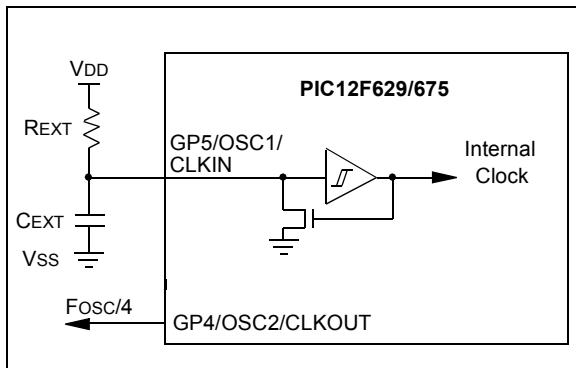
For applications where precise timing is not a requirement, the RC oscillator option is available. The operation and functionality of the RC oscillator is dependent upon a number of variables. The RC oscillator frequency is a function of:

- Supply voltage
- Resistor (REXT) and capacitor (CEXT) values
- Operating temperature.

The oscillator frequency will vary from unit to unit due to normal process parameter variation. The difference in lead frame capacitance between package types will also affect the oscillation frequency, especially for low CEXT values. The user also needs to account for the tolerance of the external R and C components. Figure 9-3 shows how the R/C combination is connected.

Two options are available for this Oscillator mode which allow GP4 to be used as a general purpose I/O or to output Fosc/4.

**FIGURE 9-3: RC OSCILLATOR MODE**



## 9.2.5 INTERNAL 4 MHz OSCILLATOR

When calibrated, the internal oscillator provides a fixed 4 MHz (nominal) system clock. See Electrical Specifications, **Section 12.0 “Electrical Specifications”**, for information on variation over voltage and temperature.

Two options are available for this Oscillator mode which allow GP4 to be used as a general purpose I/O or to output Fosc/4.

### 9.2.5.1 Calibrating the Internal Oscillator

A calibration instruction is programmed into the last location of program memory. This instruction is a RETLW XX, where the literal is the calibration value. The literal is placed in the OSCCAL register to set the calibration of the internal oscillator. Example 9-1 demonstrates how to calibrate the internal oscillator. For best operation, decouple (with capacitance) VDD and VSS as close to the device as possible.

**Note:** Erasing the device will also erase the pre-programmed internal calibration value for the internal oscillator. The calibration value must be saved prior to erasing part as specified in the PIC12F629/675 Programming specification. Microchip Development Tools maintain all Calibration bits to factory settings.

### EXAMPLE 9-1: CALIBRATING THE INTERNAL OSCILLATOR

```
BSF    STATUS, RP0    ;Bank 1
CALL   3FFh           ;Get the cal value
MOVWF  OSCCAL         ;Calibrate
BCF    STATUS, RP0    ;Bank 0
```

## 9.2.6 CLKOUT

The PIC12F629/675 devices can be configured to provide a clock out signal in the INTOSC and RC oscillator modes. When configured, the oscillator frequency divided by four (Fosc/4) is output on the GP4/OSC2/CLKOUT pin. Fosc/4 can be used for test purposes or to synchronize other logic.

## 9.3 Reset

The PIC12F629/675 differentiates between various kinds of Reset:

- Power-on Reset (POR)
- WDT Reset during normal operation
- WDT Reset during Sleep
- $\overline{\text{MCLR}}$  Reset during normal operation
- $\overline{\text{MCLR}}$  Reset during Sleep
- Brown-out Detect (BOD)

Some registers are not affected in any Reset condition; their status is unknown on POR and unchanged in any other Reset. Most other registers are reset to a "Reset state" on:

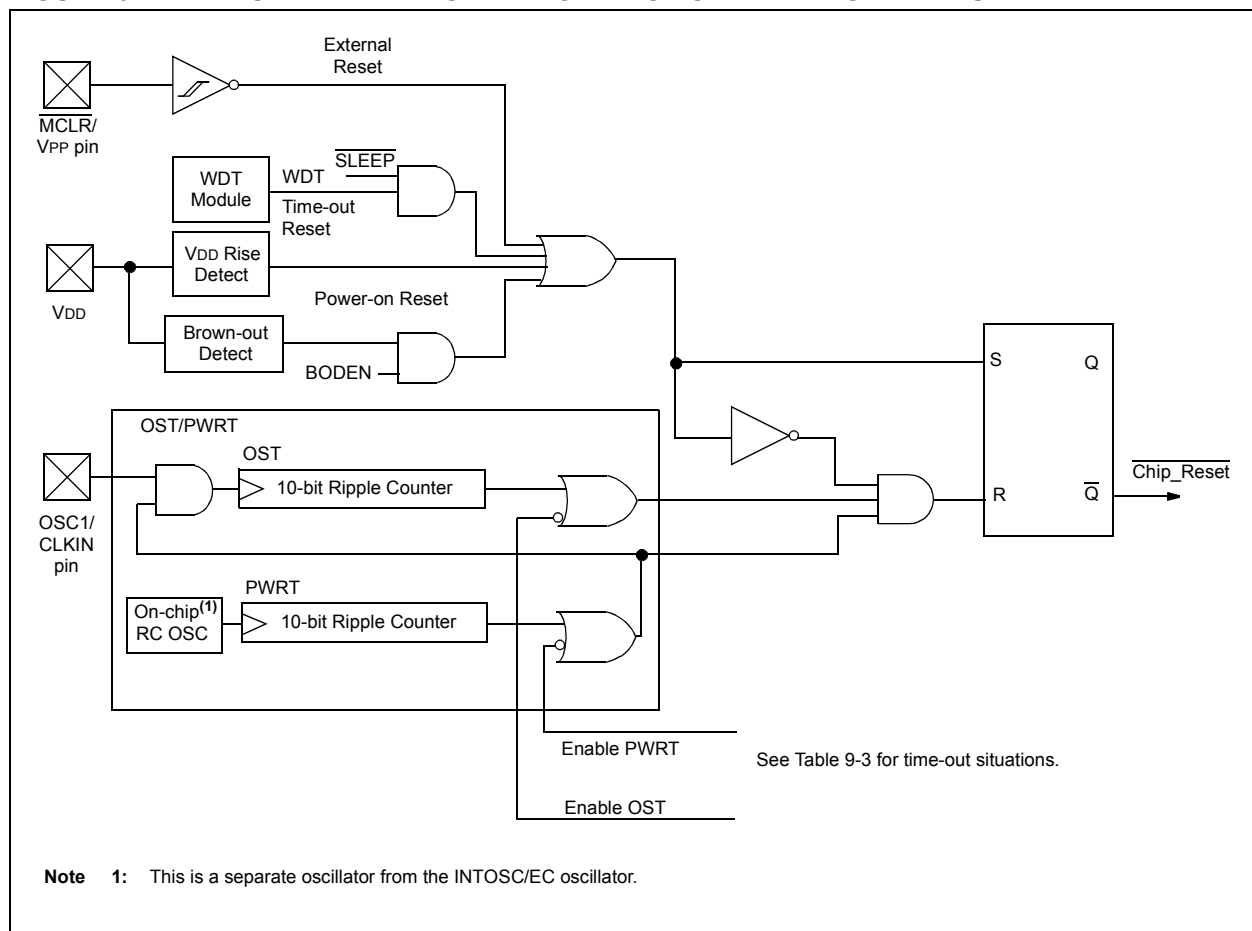
- Power-on Reset
- $\overline{\text{MCLR}}$  Reset
- WDT Reset
- WDT Reset during Sleep
- Brown-out Detect (BOD) Reset

They are not affected by a WDT wake-up, since this is viewed as the resumption of normal operation.  $\overline{\text{TO}}$  and  $\overline{\text{PD}}$  bits are set or cleared differently in different Reset situations as indicated in Table 9-4. These bits are used in software to determine the nature of the Reset. See Table 9-7 for a full description of Reset states of all registers.

A simplified block diagram of the on-chip Reset Circuit is shown in Figure 9-4.

The  $\overline{\text{MCLR}}$  Reset path has a noise filter to detect and ignore small pulses. See Table 12-4 in Electrical Specifications Section for pulse-width specification.

**FIGURE 9-4: SIMPLIFIED BLOCK DIAGRAM OF ON-CHIP RESET CIRCUIT**



# PIC12F629/675

## 9.3.1 $\overline{\text{MCLR}}$

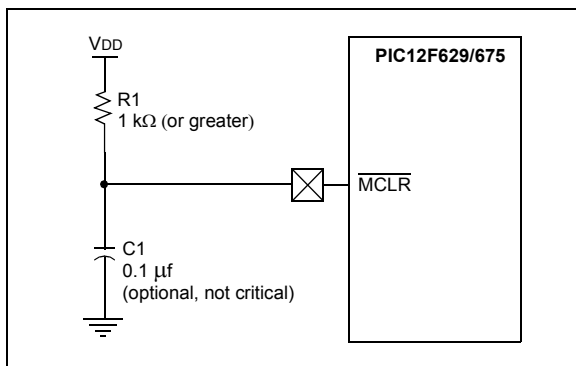
PIC12F629/675 devices have a noise filter in the  $\overline{\text{MCLR}}$  Reset path. The filter will detect and ignore small pulses.

It should be noted that a WDT Reset does not drive  $\overline{\text{MCLR}}$  pin low.

The behavior of the ESD protection on the  $\overline{\text{MCLR}}$  pin has been altered from previous devices of this family. Voltages applied to the pin that exceed its specification can result in both  $\overline{\text{MCLR}}$  Resets and excessive current beyond the device specification during the ESD event. For this reason, Microchip recommends that the  $\overline{\text{MCLR}}$  pin no longer be tied directly to VDD. The use of an RC network, as shown in Figure 9-5, is suggested.

An internal  $\overline{\text{MCLR}}$  option is enabled by setting the  $\overline{\text{MCLRE}}$  bit in the Configuration Word. When enabled,  $\overline{\text{MCLR}}$  is internally tied to VDD. No internal pull-up option is available for the  $\overline{\text{MCLR}}$  pin.

**FIGURE 9-5: RECOMMENDED  $\overline{\text{MCLR}}$  CIRCUIT**



## 9.3.2 POWER-ON RESET (POR)

The on-chip POR circuit holds the chip in Reset until VDD has reached a high enough level for proper operation. To take advantage of the POR, simply tie the  $\overline{\text{MCLR}}$  pin through a resistor to VDD. This will eliminate external RC components usually needed to create Power-on Reset. A maximum rise time for VDD is required. See Electrical Specifications for details (see **Section 12.0 “Electrical Specifications”**). If the BOD is enabled, the maximum rise time specification does not apply. The BOD circuitry will keep the device in Reset until VDD reaches VBOD (see **Section 9.3.5 “Brown-Out Detect (BOD)”**).

**Note:** The POR circuit does not produce an internal Reset when VDD declines.

When the device starts normal operation (exits the Reset condition), device operating parameters (i.e., voltage, frequency, temperature, etc.) must be met to ensure operation. If these conditions are not met, the device must be held in Reset until the operating conditions are met.

For additional information, refer to Application Note AN607, “Power-up Trouble Shooting”.

## 9.3.3 POWER-UP TIMER (PWRT)

The Power-up Timer provides a fixed 72 ms (nominal) time-out on power-up only, from POR or Brown-out Detect. The Power-up Timer operates on an internal RC oscillator. The chip is kept in Reset as long as PWRT is active. The PWRT delay allows the VDD to rise to an acceptable level. A Configuration bit,  $\overline{\text{PWRTE}}$  can disable (if set) or enable (if cleared or programmed) the Power-up Timer. The Power-up Timer should always be enabled when Brown-out Detect is enabled.

The Power-up Time delay will vary from chip to chip and due to:

- VDD variation
- Temperature variation
- Process variation.

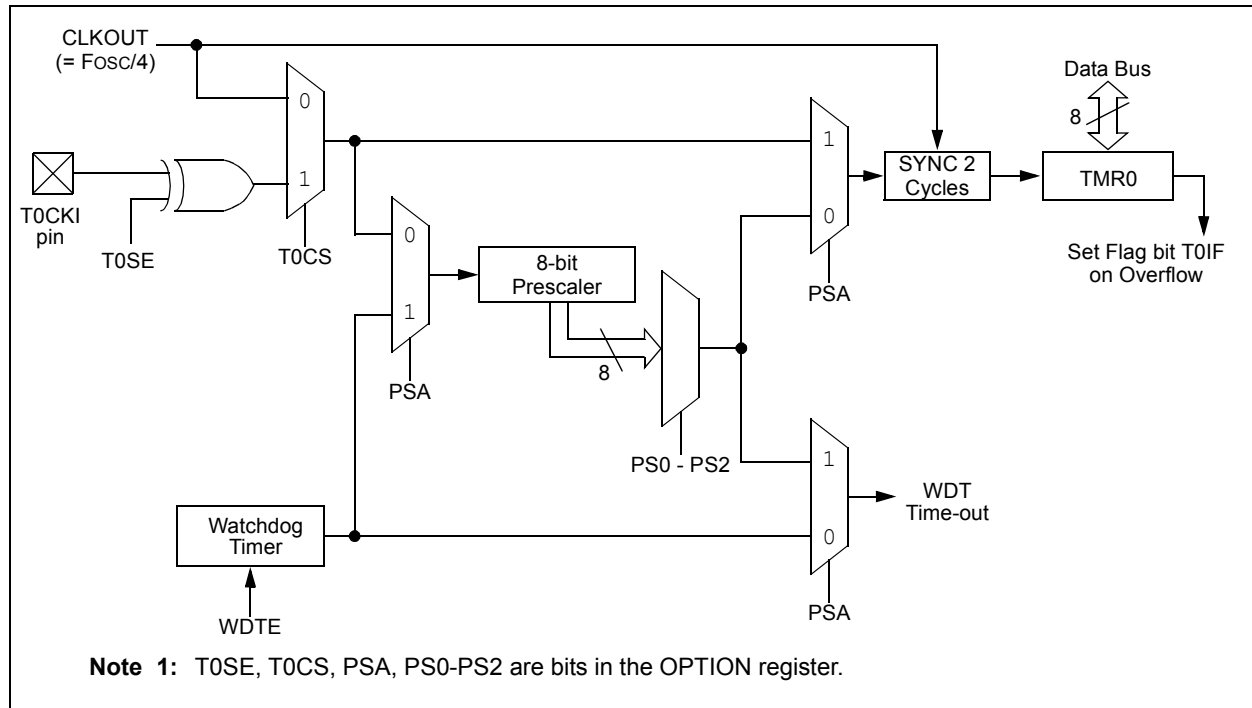
See DC parameters for details (**Section 12.0 “Electrical Specifications”**).

## 9.3.4 OSCILLATOR START-UP TIMER (OST)

The Oscillator Start-up Timer (OST) provides a 1024 oscillator cycle (from OSC1 input) delay after the PWRT delay is over. This ensures that the crystal oscillator or resonator has started and stabilized.

The OST time-out is invoked only for XT, LP and HS modes and only on Power-on Reset or wake-up from Sleep.

**FIGURE 9-12: WATCHDOG TIMER BLOCK DIAGRAM**

**TABLE 9-9: SUMMARY OF WATCHDOG TIMER REGISTERS**

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOD	Value on all other Resets
81h	OPTION_REG	$\overline{\text{GPPU}}$	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0	1111 1111	1111 1111
2007h	Config. bits	$\overline{\text{CP}}$	BODEN	MCLRE	$\overline{\text{PWRT}}\overline{\text{E}}$	WDTE	F0SC2	F0SC1	F0SC0	uuuu uuuu	uuuu uuuu

**Legend:** u = Unchanged, shaded cells are not used by the Watchdog Timer.

<b>XORLW</b>	<b>Exclusive OR Literal with W</b>
Syntax:	<i>[label]</i> XORLW k
Operands:	$0 \leq k \leq 255$
Operation:	(W) .XOR. k $\rightarrow$ (W)
Status Affected:	Z
Description:	The contents of the W register are XOR'ed with the eight-bit literal 'k'. The result is placed in the W register.

<b>XORWF</b>	<b>Exclusive OR W with f</b>
Syntax:	<i>[label]</i> XORWF f,d
Operands:	$0 \leq f \leq 127$ $d \in [0,1]$
Operation:	(W) .XOR. (f) $\rightarrow$ (destination)
Status Affected:	Z
Description:	Exclusive OR the contents of the W register with register 'f'. If 'd' is 0, the result is stored in the W register. If 'd' is 1, the result is stored back in register 'f'.

## 11.11 PICKit 2 Development Programmer/Debugger and PICKit 2 Debug Express

The PICKit™ 2 Development Programmer/Debugger is a low-cost development tool with an easy to use interface for programming and debugging Microchip's Flash families of microcontrollers. The full featured Windows® programming interface supports baseline (PIC10F, PIC12F5xx, PIC16F5xx), midrange (PIC12F6xx, PIC16F), PIC18F, PIC24, dsPIC30, dsPIC33, and PIC32 families of 8-bit, 16-bit, and 32-bit microcontrollers, and many Microchip Serial EEPROM products. With Microchip's powerful MPLAB Integrated Development Environment (IDE) the PICKit™ 2 enables in-circuit debugging on most PIC® microcontrollers. In-Circuit-Debugging runs, halts and single steps the program while the PIC microcontroller is embedded in the application. When halted at a breakpoint, the file registers can be examined and modified.

The PICKit 2 Debug Express include the PICKit 2, demo board and microcontroller, hookup cables and CDROM with user's guide, lessons, tutorial, compiler and MPLAB IDE software.

## 11.12 MPLAB PM3 Device Programmer

The MPLAB PM3 Device Programmer is a universal, CE compliant device programmer with programmable voltage verification at VDDMIN and VDDMAX for maximum reliability. It features a large LCD display (128 x 64) for menus and error messages and a modular, detachable socket assembly to support various package types. The ICSP™ cable assembly is included as a standard item. In Stand-Alone mode, the MPLAB PM3 Device Programmer can read, verify and program PIC devices without a PC connection. It can also set code protection in this mode. The MPLAB PM3 connects to the host PC via an RS-232 or USB cable. The MPLAB PM3 has high-speed communications and optimized algorithms for quick programming of large memory devices and incorporates an MMC card for file storage and data applications.

## 11.13 Demonstration/Development Boards, Evaluation Kits, and Starter Kits

A wide variety of demonstration, development and evaluation boards for various PIC MCUs and dsPIC DSCs allows quick application development on fully functional systems. Most boards include prototyping areas for adding custom circuitry and provide application firmware and source code for examination and modification.

The boards support a variety of features, including LEDs, temperature sensors, switches, speakers, RS-232 interfaces, LCD displays, potentiometers and additional EEPROM memory.

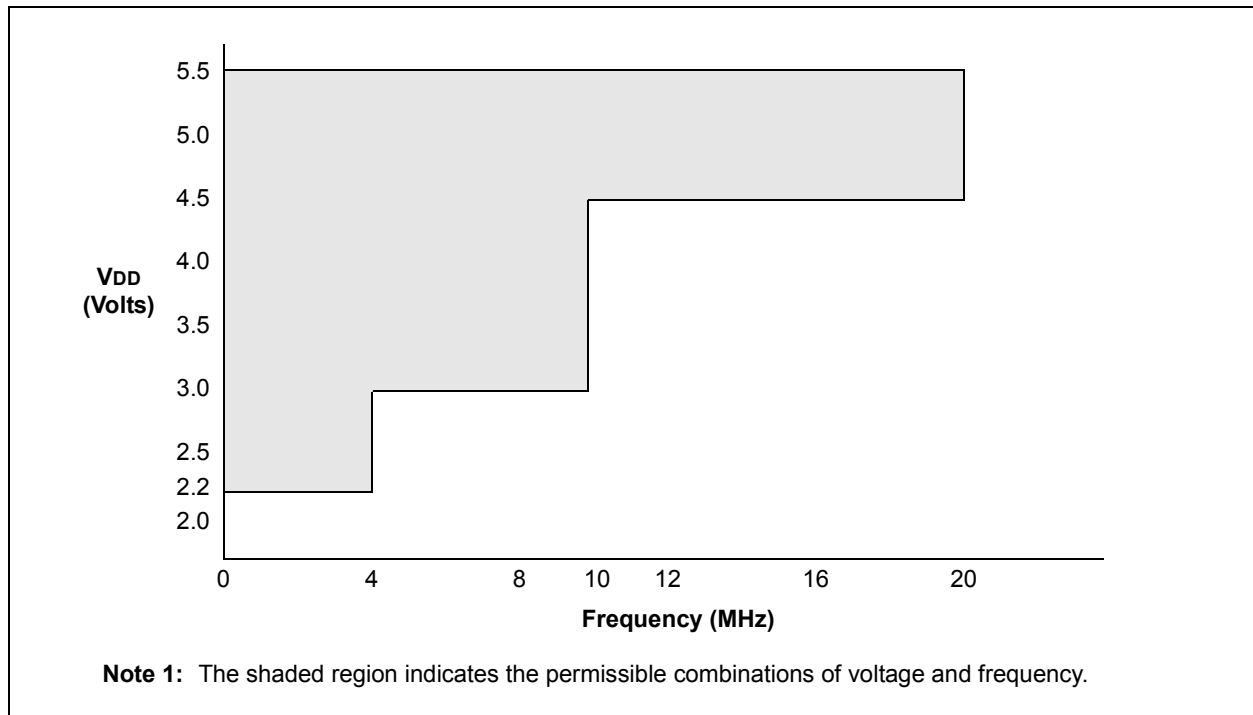
The demonstration and development boards can be used in teaching environments, for prototyping custom circuits and for learning about various microcontroller applications.

In addition to the PICDEM™ and dsPICDEM™ demonstration/development board series of circuits, Microchip has a line of evaluation kits and demonstration software for analog filter design, KEELOQ® security ICs, CAN, IrDA®, PowerSmart battery management, SEEVAL® evaluation system, Sigma-Delta ADC, flow rate sensing, plus many more.

Also available are starter kits that contain everything needed to experience the specified device. This usually includes a single application and debug capability, all on one board.

Check the Microchip web page ([www.microchip.com](http://www.microchip.com)) for the complete list of demonstration, development and evaluation kits.

**FIGURE 12-3: PIC12F675 WITH A/D ENABLED VOLTAGE-FREQUENCY GRAPH,  
 $0^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$**



# PIC12F629/675

## 12.1 DC Characteristics: PIC12F629/675-I (Industrial), PIC12F629/675-E (Extended)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated)				
			Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended				
Param No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
D001 D001A D001B D001C D001D	VDD	<b>Supply Voltage</b>	2.0 2.2 2.5 3.0 4.5	— — — — —	5.5 5.5 5.5 5.5 5.5	V V V V V	FOSC $\leq 4$ MHz: PIC12F629/675 with A/D off PIC12F675 with A/D on, $0^{\circ}\text{C}$ to $+125^{\circ}\text{C}$ PIC12F675 with A/D on, $-40^{\circ}\text{C}$ to $+125^{\circ}\text{C}$ $4\text{ MHz} < \text{FOSC} \leq 10\text{ MHz}$
D002	VDR	<b>RAM Data Retention Voltage<sup>(1)</sup></b>	1.5*	—	—	V	Device in Sleep mode
D003	VPOR	<b>VDD Start Voltage</b> to ensure internal Power-on Reset signal	—	VSS	—	V	See section on Power-on Reset for details
D004	SVDD	<b>VDD Rise Rate</b> to ensure internal Power-on Reset signal	0.05*	—	—	V/ms	See section on Power-on Reset for details
D005	VBOD		—	2.1	—	V	

\* These parameters are characterized but not tested.

† Data in "Typ" column is at 5.0V,  $25^{\circ}\text{C}$  unless otherwise stated. These parameters are for design guidance only and are not tested.

**Note 1:** This is the limit to which VDD can be lowered in Sleep mode without losing RAM data.



## 12.2 DC Characteristics: PIC12F629/675-I (Industrial)

		Standard Operating Conditions (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial					
Param No.	Device Characteristics	Min	Typ†	Max	Units	Conditions	
						VDD	Note
D010	Supply Current (IDD)	—	9	16	μA	2.0	Fosc = 32 kHz LP Oscillator Mode
		—	18	28	μA	3.0	
		—	35	54	μA	5.0	
D011		—	110	150	μA	2.0	Fosc = 1 MHz XT Oscillator Mode
		—	190	280	μA	3.0	
		—	330	450	μA	5.0	
D012		—	220	280	μA	2.0	Fosc = 4 MHz XT Oscillator Mode
		—	370	650	μA	3.0	
		—	0.6	1.4	mA	5.0	
D013		—	70	110	μA	2.0	Fosc = 1 MHz EC Oscillator Mode
		—	140	250	μA	3.0	
		—	260	390	μA	5.0	
D014		—	180	250	μA	2.0	Fosc = 4 MHz EC Oscillator Mode
		—	320	470	μA	3.0	
		—	580	850	μA	5.0	
D015		—	340	450	μA	2.0	Fosc = 4 MHz INTOSC Mode
		—	500	700	μA	3.0	
		—	0.8	1.1	mA	5.0	
D016		—	180	250	μA	2.0	Fosc = 4 MHz EXTRC Mode
		—	320	450	μA	3.0	
		—	580	800	μA	5.0	
D017		—	2.1	2.95	mA	4.5	Fosc = 20 MHz HS Oscillator Mode
		—	2.4	3.0	mA	5.0	

† Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

**Note 1:** The test conditions for all I<sub>DD</sub> measurements in Active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to V<sub>DD</sub>; MCLR = V<sub>DD</sub>; WDT disabled.

**2:** The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.

12.8 TIMING PARAMETER SYMBOLOGY

The timing parameter symbols have been created with one of the following formats:

- 1. TppS2ppS
- 2. TppS

<b>T</b>			
F	Frequency	T	Time

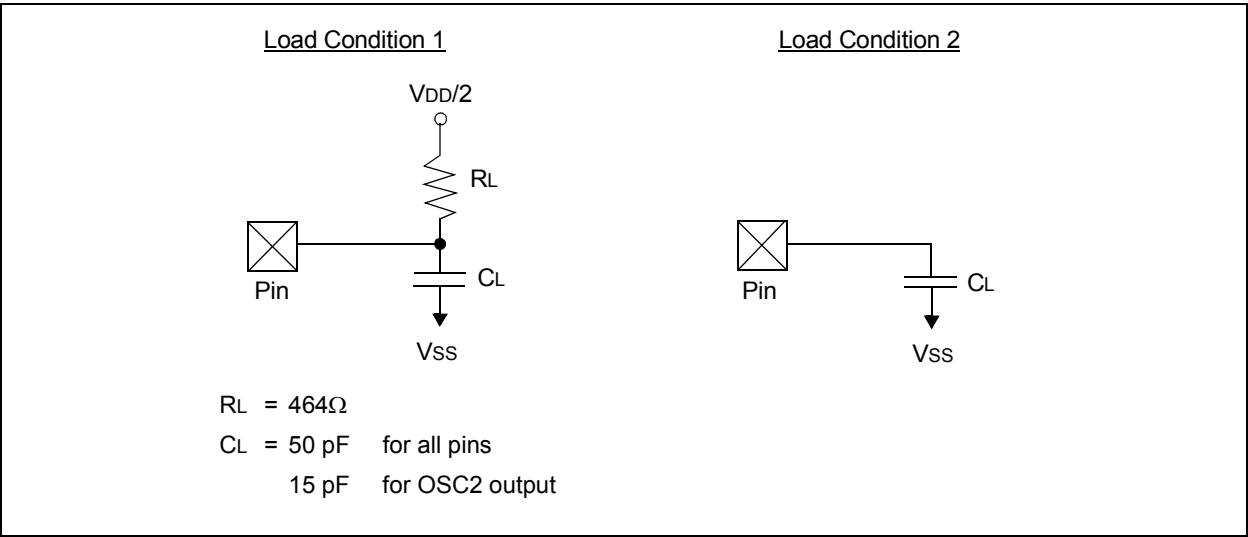
Lowercase letters (pp) and their meanings:

<b>pp</b>			
cc	CCP1	osc	OSC1
ck	CLKOUT	rd	$\overline{RD}$
cs	$\overline{CS}$	rw	$\overline{RD}$ or $\overline{WR}$
di	SDI	sc	SCK
do	SDO	ss	$\overline{SS}$
dt	Data in	t0	T0CKI
io	I/O port	t1	T1CKI
mc	$\overline{MCLR}$	wr	$\overline{WR}$

Uppercase letters and their meanings:

<b>S</b>			
F	Fall	P	Period
H	High	R	Rise
I	Invalid (High-Impedance)	V	Valid
L	Low	Z	High-Impedance

FIGURE 12-4: LOAD CONDITIONS



# PIC12F629/675

**TABLE 12-6: COMPARATOR SPECIFICATIONS**

Comparator Specifications		Standard Operating Conditions -40°C to +125°C (unless otherwise stated)				
Sym	Characteristics	Min	Typ	Max	Units	Comments
VOS	Input Offset Voltage	—	± 5.0	± 10	mV	
VCM	Input Common Mode Voltage	0	—	VDD - 1.5	V	
CMRR	Common Mode Rejection Ratio	+55*	—	—	db	
TRT	Response Time <sup>(1)</sup>	—	150	400*	ns	
TMC2COV	Comparator Mode Change to Output Valid	—	—	10*	µs	

\* These parameters are characterized but not tested.

**Note 1:** Response time measured with one comparator input at (VDD - 1.5)/2 while the other input transitions from VSS to VDD - 1.5V.

**TABLE 12-7: COMPARATOR VOLTAGE REFERENCE SPECIFICATIONS**

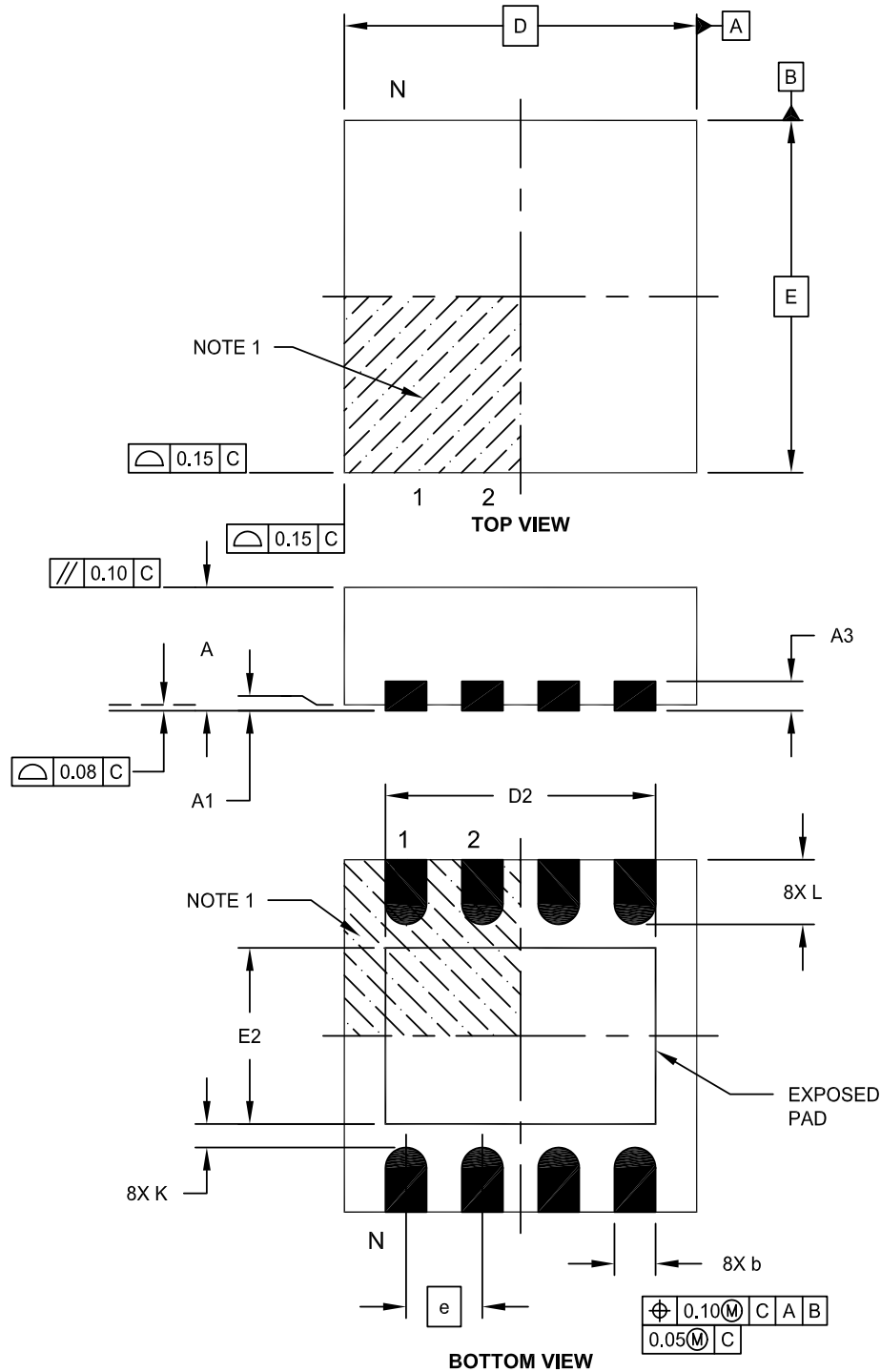
Voltage Reference Specifications		Standard Operating Conditions -40°C to +125°C (unless otherwise stated)				
Sym	Characteristics	Min	Typ	Max	Units	Comments
	Resolution	—	VDD/24*	—	LSb	Low Range (VRR = 1)
		—	VDD/32	—	LSb	High Range (VRR = 0)
	Absolute Accuracy	—	—	± 1/2	LSb	Low Range (VRR = 1)
		—	—	± 1/2*	LSb	High Range (VRR = 0)
	Unit Resistor Value (R)	—	2k*	—	Ω	
	Settling Time <sup>(1)</sup>	—	—	10*	µs	

\* These parameters are characterized but not tested.

**Note 1:** Settling time measured while VRR = 1 and VR<3:0> transitions from 0000 to 1111.

## 8-Lead Plastic Dual Flat, No Lead Package (MD) – 4x4x0.9 mm Body [DFN]

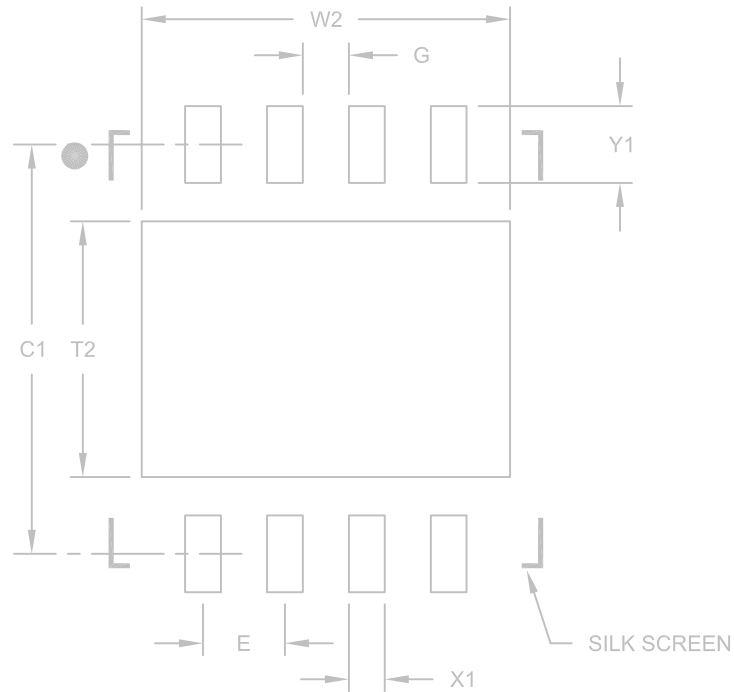
**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Microchip Technology Drawing C04-131E Sheet 1 of 2

## 8-Lead Plastic Dual Flat, No Lead Package (MD) – 4x4x0.9 mm Body [DFN]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.80 BSC		
Optional Center Pad Width	W2			3.60
Optional Center Pad Length	T2			2.50
Contact Pad Spacing	C1		4.00	
Contact Pad Width (X8)	X1			0.35
Contact Pad Length (X8)	Y1			0.75
Distance Between Pads	G	0.45		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2131B